

Title (en)

Enhanced surface preparation process for application of ceramic coatings

Title (de)

Verbesserte Vorbereitung einer Oberfläche zum Auftragen von keramischen Beschichtungen

Title (fr)

Préparation améliorée d'une surface pour l'application de revêtements céramiques

Publication

**EP 1217089 A3 20030402 (EN)**

Application

**EP 01310695 A 20011220**

Priority

US 74771300 A 20001222

Abstract (en)

[origin: EP1217089A2] Metallic surfaces are prepared to receive ceramic coatings. An abrasion process of progressively declining intensity removes a portion of the metallic surface. Ceramic coating applied to surfaces so prepared display improved lives at elevated temperatures. <IMAGE>

IPC 1-7

**C23C 4/02**; **C23C 14/02**

IPC 8 full level

**F01D 5/28** (2006.01); **C23C 4/02** (2006.01); **C23C 4/073** (2016.01); **C23C 4/08** (2016.01); **C23C 4/10** (2016.01); **C23C 4/11** (2016.01); **C23C 14/02** (2006.01); **C23C 28/00** (2006.01); **C23C 30/00** (2006.01)

CPC (source: EP US)

**C23C 4/02** (2013.01 - EP US); **C23C 14/028** (2013.01 - EP US); **C23C 28/3215** (2013.01 - EP US); **C23C 28/325** (2013.01 - EP US); **C23C 28/3455** (2013.01 - EP US); **Y10T 428/12472** (2015.01 - EP US); **Y10T 428/12618** (2015.01 - EP US); **Y10T 428/12944** (2015.01 - EP US)

Citation (search report)

- [XA] WO 0115866 A1 20010308 - SIEMENS AG [DE], et al
- [A] US 4514469 A 19850430 - LOERSCH JOSEPH F [US], et al
- [A] US 4287740 A 19810908 - KUMAR ARUN

Cited by

EP3892750A1; CN106811729A; DE102004045049A1; CN103781588A; EP2180086A1; CN101746090A; US10408079B2; US7736704B2; US9664201B2; WO2021204596A1; WO2013021141A1; US10190435B2; US10189082B2; US9920646B2; US10221716B2; US10196920B2; US10323533B2

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

**EP 1217089 A2 20020626**; **EP 1217089 A3 20030402**; **EP 1217089 B1 20050309**; **EP 1217089 B2 20130508**; DE 60109257 D1 20050414; DE 60109257 T2 20050728; DE 60109257 T3 20130704; JP 2002275658 A 20020925; SG 114515 A1 20050928; US 2003039764 A1 20030227

DOCDB simple family (application)

**EP 01310695 A 20011220**; DE 60109257 T 20011220; JP 2001391678 A 20011225; SG 200107598 A 20011207; US 74771300 A 20001222